

	Type	L #	Hits	Search Text	DBs
1	IS&R	L1	1	("6004405").PN.	USPAT
2	BRS	L2	3	("4418467"   "5800906"   "5876819").PN.	US-PGPUB; USPAT; USOCR
3	BRS	L3	15	("6004405").URPN.	USPAT
4	BRS	L4	101750	semiconductor and wafer	USPAT
5	BRS	L5	1619	4 and (bevel or chamfer\$4)	USPAT
6	BRS	L6	838	5 and (ID or mark or marking or groove)	USPAT
7	BRS	L7	65	5 and identification	USPAT
8	BRS	L8	28	5 and label	USPAT
9	BRS	L9	778	5 and (groove or dot or bar)	USPAT

	Type	L #	Hits	Search Text	DBs
1	BRS	L1	182082	semiconductor and wafer	US-PGPUB; USOCR; EPO; JPO; DERWENT; IBM_TDB
2	BRS	L2	1937	1 and (bevel or chamfer\$4)	US-PGPUB; USOCR; EPO; JPO; DERWENT; IBM_TDB
3	BRS	L4	59	2 and identification	US-PGPUB; USOCR; EPO; JPO; DERWENT; IBM_TDB
4	BRS	L5	24	2 and label	US-PGPUB; USOCR; EPO; JPO; DERWENT; IBM_TDB
5	BRS	L6	599	2 and (groove or dot or bar)	US-PGPUB; USOCR; EPO; JPO; DERWENT; IBM_TDB
6	BRS	L3	649	2 and (ID or mark or marking or groove)	US-PGPUB; USOCR; EPO; JPO; DERWENT; IBM_TDB